

AMENDMENTS TO THE SPECIFICATION AND ABSTRACT

On Page 61, paragraph [0097] please amend the paragraph as follow:

[0097] The wiring board is obtained by superposing the wiring transfer sheet on an electrically insulating substrate for a wiring board with the wiring layer in contact with a surface of the electrically insulating substrate followed by heating and pressurization so as to transfer the wiring layer to the electrically insulating substrate. The structure of the wiring layer thus obtained is as shown Fig. 1(d). In this wiring board 110, the wiring layer 103 (formerly wiring layer 102 on carrier base 101) is entirely buried in the electrically insulating substrate 104, and an exposed surface of the wiring layer 103 is flush with an exposed surface of the electrically insulating substrate 104. This is because the wiring layer 102 protrudes in the wiring transfer sheet 100 shown in Fig. 1(a). During the step of transferring the wiring layer, pressure is applied so that the wiring layer is brought into contact with the object without a gap therebetween, whereby the protruding wiring layer is buried in the electrically insulating substrate.

On Page 63, paragraph [0099] please amend the paragraph as follow:

[0099] Further, as shown in Fig. 1(f), this wiring board has fine convexities on a surface of the wiring layer 103 (formerly wiring layer 102). This is because the interface between the wiring layer 102 (i.e., wiring layer 103 before transfer) and the carrier base 101 ~~103~~ is uneven in the wiring transfer sheet, and the convexities of the wiring layer 102 are exposed by peeling off the carrier base after the wiring layer has been transferred. Thus, because the surface shape (having the convexities) of the exposed surface of the wiring layer 103 and the surface shape (having the convexities) of the exposed surface of the insulating substrate 104 are both formed by the surface shape (having the concavities) of the carrier base 101 of transfer sheet 100, the surface shape of the exposed surfaces of the wiring layer 103 and the insulating substrate 104 are substantially the same, as illustrated in Fig. 1(f). The convexities on the wiring layer 103, as well as the convexities on the electrically insulating substrate 104, contribute to the increase of the contact area between the wiring layer and the stacked resin, and provide an anchoring effect. Therefore,

this wiring board in which the convexities exist on not only the surface of the electrically insulating substrate but also the surface of the wiring layer, strongly adheres to the resin stacked thereon.